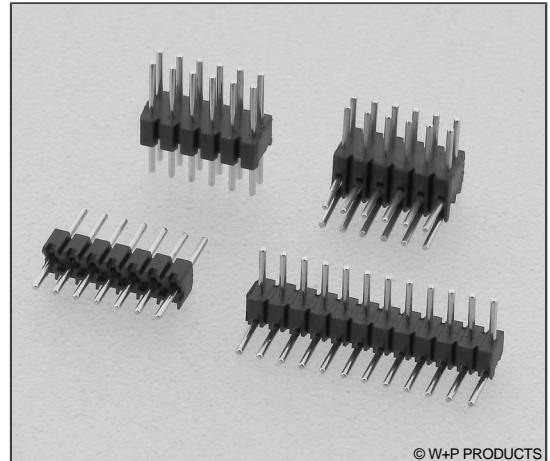


Stiftleisten RM 1,27mm, gerade/gewinkelt, 1-/2-reihig – Rundstifte 0,42mm Pin Headers, 1.27mm Pitch, Straight/Right-Angled, Single/Double Row – 0.42mm Round Pins

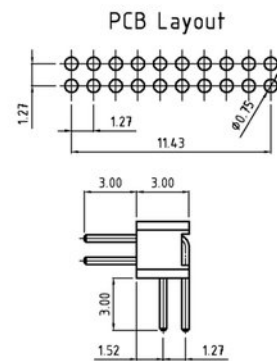
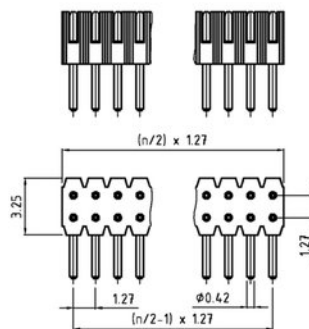
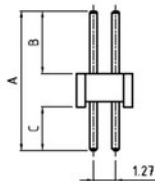
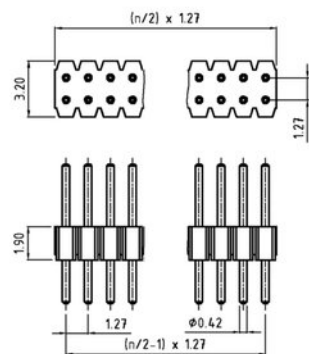
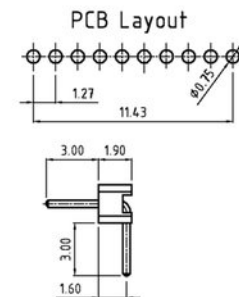
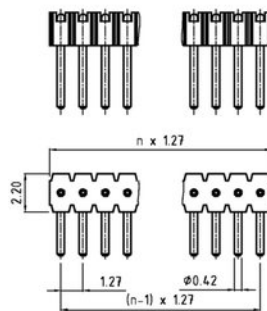
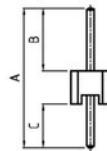
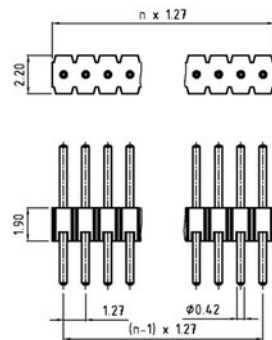
Technische Daten / Technical Data

Isolierkörper <i>Insulator</i>	Thermoplast, nach UL94 V-0 <i>Thermoplastic, rated UL94 V-0</i>
Kontaktmaterial <i>Contact Material</i>	Rundstift Ø0,42mm, Kupferlegierung <i>Ø0,42mm round pin, copper alloy</i>
Kontaktoberfläche <i>Contact Surface</i>	Lt. Oberflächenoptionen, über Ni (1,3 ... 2,5µm) <i>Acc. to options (see below), over Ni (1.3 ... 2.5µm)</i>
Durchgangswiderstand <i>Contact Resistance</i>	< 20 mΩ <i>< 20 mΩ</i>
Isolationswiderstand <i>Insulation Resistance</i>	> 1000 MΩ <i>> 1000 MΩ</i>
Spannungsfestigkeit <i>Test Voltage</i>	500 V AC <i>500 V AC</i>
Nennstrom <i>Current Rating</i>	1 A <i>1 A</i>
Temperaturbereich <i>Temperature Range</i>	-55 °C ... +125 °C <i>-55 °C ... +125 °C</i>
Verarbeitung <i>Processing</i>	Wellen- oder Reflow-Lötverfahren <i>Wave or reflow soldering</i>



© W+P PRODUCTS

Passende Buchsenleisten:
Compatible Female Headers:
155 etc.
Weitere siehe Kapitel B
Please see ch. B for more



Series

755

Dimensions*

07

07 A=8,00 B=3,60 C=2,50mm
09 A=8,60 B=4,20 C=2,50mm
13 A=12,90 B=8,50 C=2,50mm
91 Einreihig, gewinkelt (s. Zng.)
Single row, right-angled (as shown in dwg.)
92 Zweireihig, gewinkelt (s. Zng.)
Dual row, right-angled (as shown in dwg.)
99 Kundenspezifisch
Customer-specific

Type*

10

10 Einreihig, gerade
Single row, straight
11 Einreihig, gewinkelt (nur Dim. Code 91)
Single row, right-angled (dim. code 91 only)
20 Zweireihig, gerade
Double row, straight
21 Zweireihig, gewinkelt (nur Dim.Code 92)
Double row, right-angled (dim. code 92 only)

Contacts*

001

001-050 Einreihig
Single row
002-100 Zweireihig
Double row

Plating*

00

00 Vergoldet
Gold plated
50 Verzinkt
Tin plated

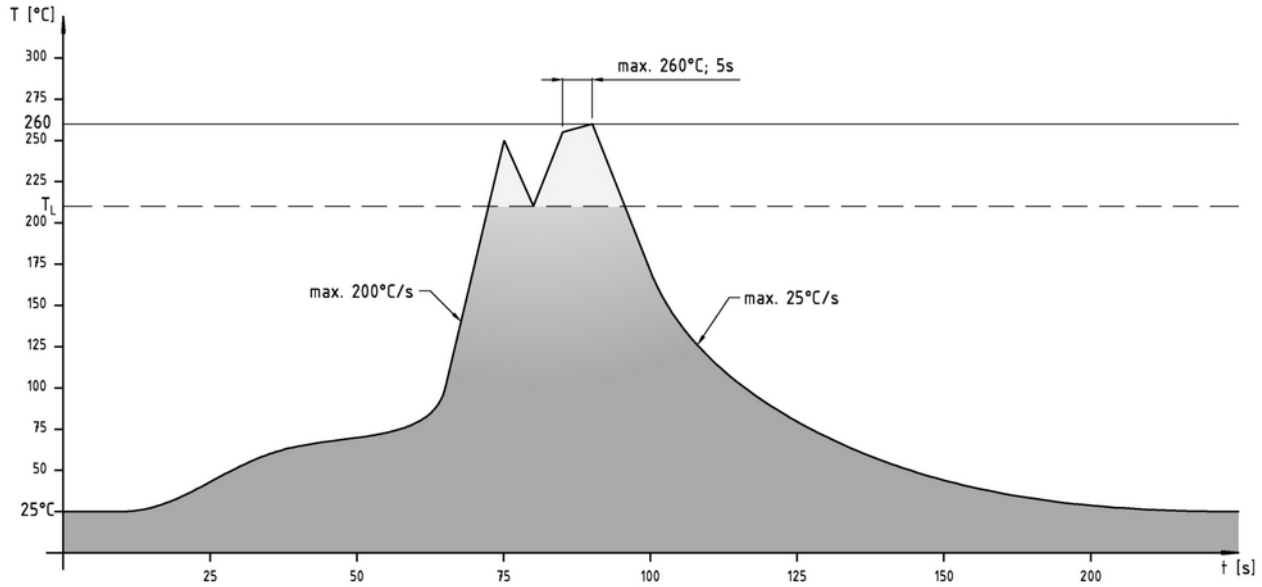
* Dies ist ein **Bestellbeispiel** -
 bitte durch Ihre Spezifikationen ersetzen.
 * This is an **order example** -
 please replace by your specifications.

Empfehlungen für das Wellenlötverfahren

Recommendations for Wave Soldering

Die Bauteile sollten bei einer Lötbadtemperatur von 260°C in max. 5 Sekunden verlötet werden.
Items should be soldered at a solder temperature of 260°C in 5 seconds max.

Empfohlenes Wellenlötprofil:
Recommended wave soldering profile:



Reflow-Lötempfehlung

Reflow Soldering Recommendation

Die Bauteile sollten gemäß folgendem Temperatur-Profil in Anlehnung an die IPC/JEDEC J-STD-020C für bleifreies Lötten im Reflow-Verfahren verarbeitet werden (Maximalwerte).

Profileigenschaft	Kennwert
Temperatur Minimum T_{Smin}	150 °C
Temperatur Maximum T_{Smax}	200 °C
Dauer $T_{Smin} - T_{Smax}$	60 – 180s
Temperatur Lötbereich T_L	217 °C
Verweildauer oberhalb T_L	60 – 180s
Ramp-Up Rate $T_{Smax} - T_P$	max. 3 °C / s
Höchsttemperatur T_P	260±5 °C
Dauer Höchsttemperatur	20 – 40s
Ramp-Down Rate $T_{Pmax} - T_{Smin}$	6 °C / s
Dauer 25 °C – Höchsttemperatur T_P	max. 8m

Items should be soldered according to IPC/JEDEC J-STD-020C temperature profile for leadfree reflow soldering (maximum values).

Profile Feature	Key Values
Minimum Temperature T_{Smin}	150 °C
Maximum Temperatur T_{Smax}	200 °C
Duration $T_{Smin} - T_{Smax}$	60 – 180s
Soldering Range Temperature T_L	217 °C
Duration above T_L	60 – 180s
Ramp-Up Rate $T_{Smax} - T_P$	max. 3 °C / s
Peak Temperature T_P	260±5 °C
Duration Peak Temperature	20 – 40s
Ramp-Down Rate $T_{Pmax} - T_{Smin}$	6 °C / s
Duration 25°C - Peak Temp. T_P	max. 8min

